3.5mm Dia. Jacks

■ Features

1. A small ø3.5mm jack that was developed for small, mobile equipment.
2. A wide selection is available including surface mounting, DIP, and mid mount types.

■ 特長

1. 小型携帯機器用に開発したø3.5mmの小型ジャックです。
2. 面実装タイプ、DIPタイプ、ミッドマウントタイプなど各種レパートリーを揃えています。

■ Specification

1.Electric Performance

Rating	: 1A, 12V DC
Contact Resistance	: 30mΩ max, 50mΩ max.
Insulation Resistance	: 100MΩ min.500V DC
Withstanding Voltage	: 500V AC(for one minute)

2.Mechanical Performance

Insertion Force	: 35N max. at 3.5mm Dia.gauge
Withdrawal Force	: 3 to 35N at 3.5mm Dia.gauge

■ 仕様

1. 電気的性能

定格電圧電流	：DC12V 1A
接触抵抗	：30mΩ以下、50mΩ以下
絶縁抵抗	：DC500V 100MΩ以上
耐電圧	：AC500V（1分間）

2.機械的性能（詳細は個別規格による）

挿入力	：ø3.5mmゲージ　35N以下
抜去力	：ø3.5mmゲージ　3 ～ 35N

■ Application

Smart phones, mobile phones, tablet PCs, portable audio, other small AV equipment.

■ 用途

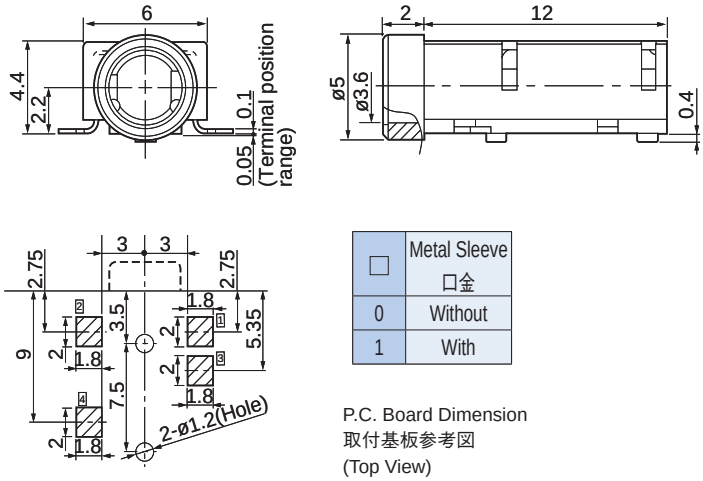
スマートフォン、携帯電話、タブレット型PC、ポータブルオーディオ、他小型AV機器

LGY22□9-0101F

SMD Type

面実装タイプ

(LGY2209-0101F)

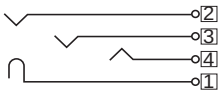


(500pcs/reel)

□	Metal Sleeve 口金
0	Without
1	With

P.C. Board Dimension
取付基板参考図
(Top View)

Circuits / 回路

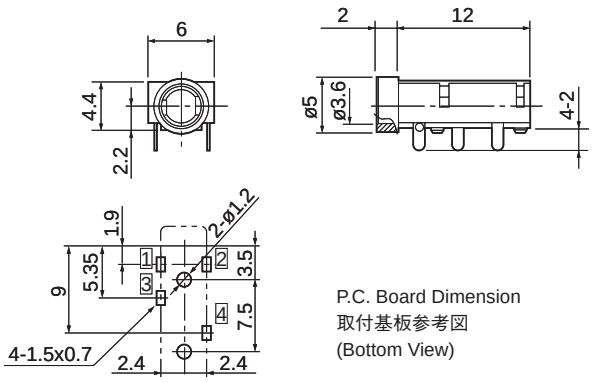


Reflow Soldering
リフローはんだ

LGY2209-03□□F

DIP Type

ディップタイプ

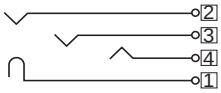


[t=0.8]

□□	Housing Color
00	Black

P.C. Board Dimension
取付基板参考図
(Bottom View)

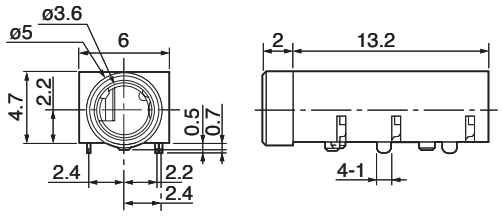
Circuits / 回路

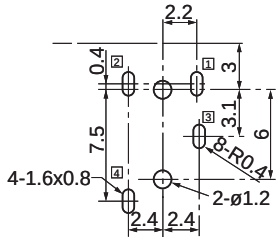


Manual Soldering
手はんだ

3.5mm Dia. Jacks

LGY2209-0801F



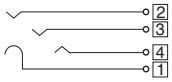


P.C. Board Dimension
取付基板参考図
(Bottom View)

※Shading Type
遮光仕様

[t=0.8]

Circuits / 回路

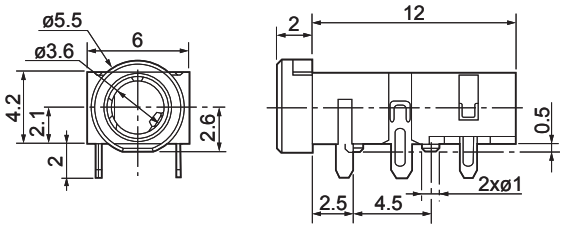


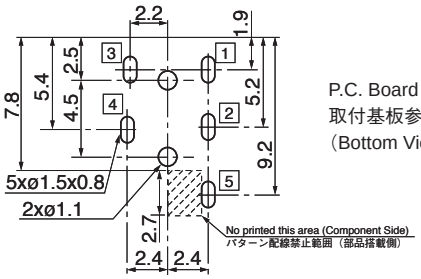
DIP Type

ディップタイプ

Reflow Soldering
リフローはんだ
Manual Soldering
手はんだ

LGY2109-0200F

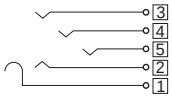




P.C. Board Dimension
取付基板参考図
(Bottom View)

[t=1.0]

Circuits / 回路

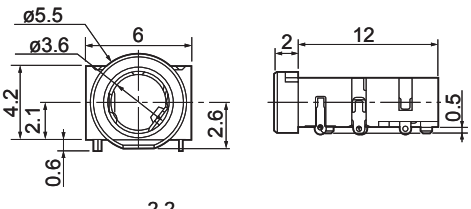


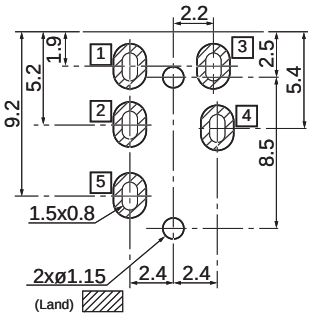
DIP Type

ディップタイプ

Manual Soldering
手はんだ

LGY2109-1701F

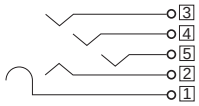




P.C. Board Dimension
取付基板参考図
(Top View)

[t=0.8]

Circuits / 回路



DIP Type

ディップタイプ

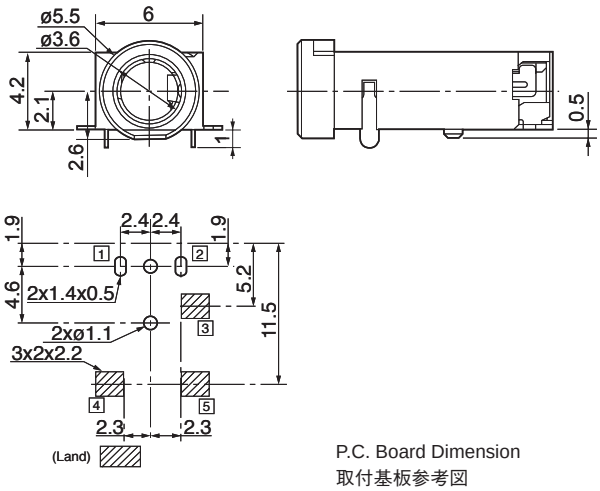
Reflow Soldering
リフローはんだ
Manual Soldering
手はんだ

3.5mm Dia. Jacks

LGY2109-3301F

DIP / SMD Type

ディップ／面実装タイプ



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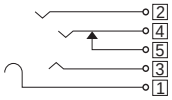
P.C. Board Dimension
取付基板参考図
(Top View)

Circuits / 回路



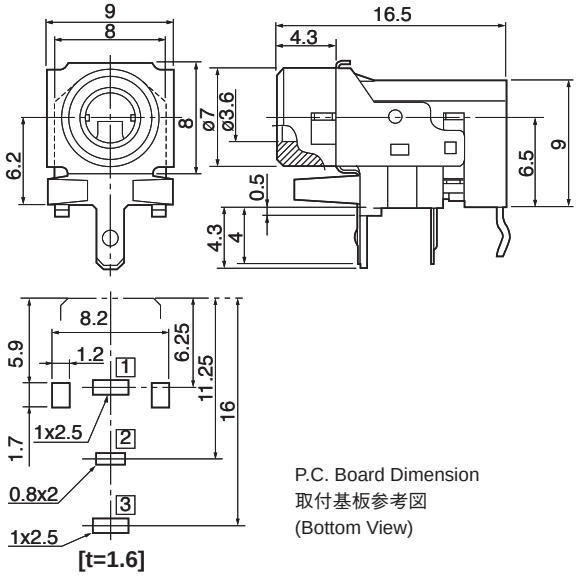
Reflow Soldering
リフローはんだ

LGY6502-0800F

DIP Type

ディップタイプ

Noise-Resistant Designed (With Earth Plate)
ノイズ対策品 (アースプレート付)



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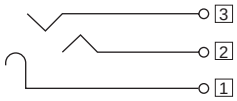
P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

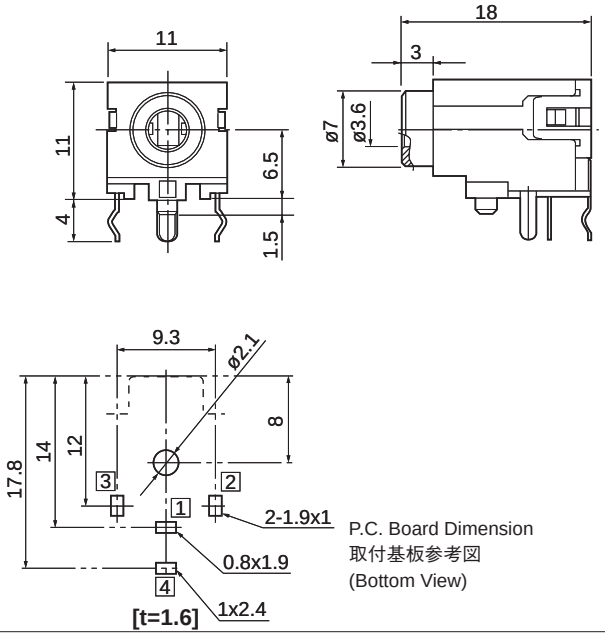


Flow Soldering
フローはんだ

LGY6509-0100F

DIP Type

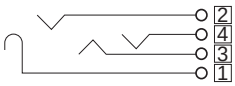
ディップタイプ



[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路



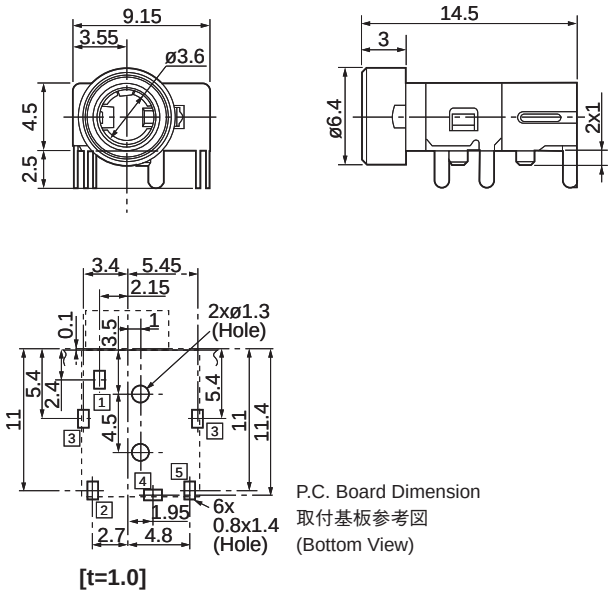
Flow Soldering
フローはんだ

3.5mm Dia. Jacks

LGS2318-0100F

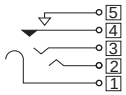
DIP Type

ディップタイプ



P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

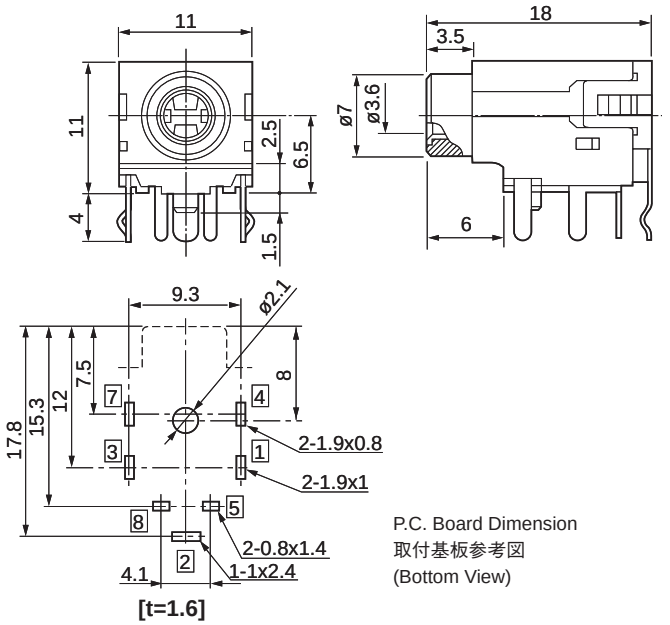


Manual Soldering
手はんだ

LGS6506-0700F

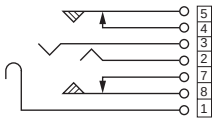
DIP Type

ディップタイプ



P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

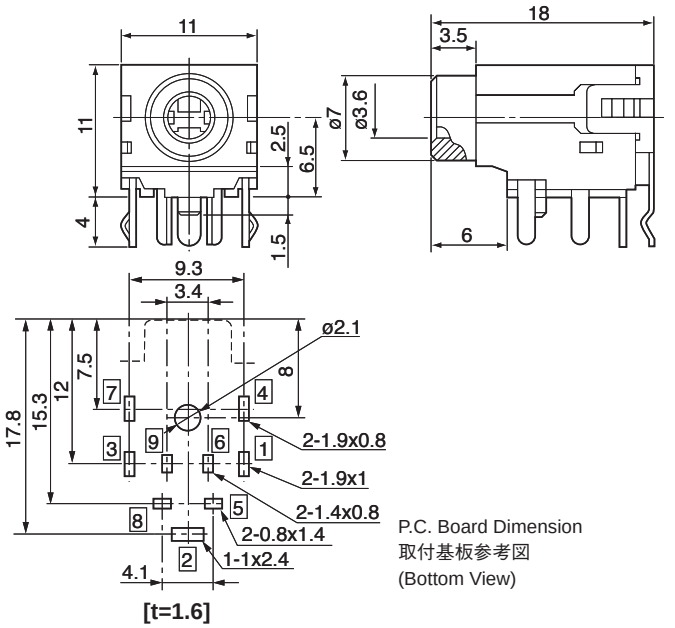


Flow Soldering
フローはんだ

LGS6507-1300F

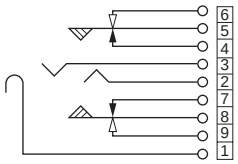
DIP Type

ディップタイプ



P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路



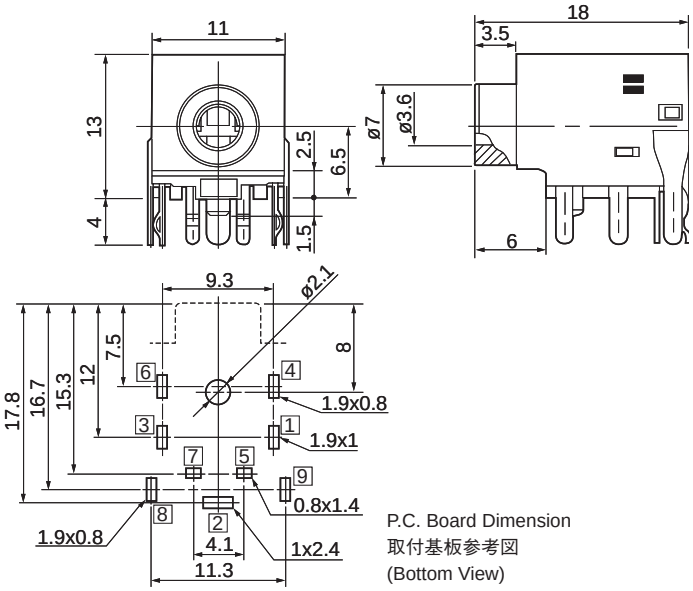
Flow Soldering
フローはんだ

3.5mm Dia. Jacks

LGS6509-1000F

DIP Type

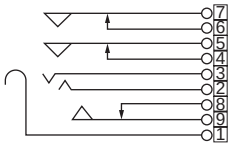
ディップタイプ



[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

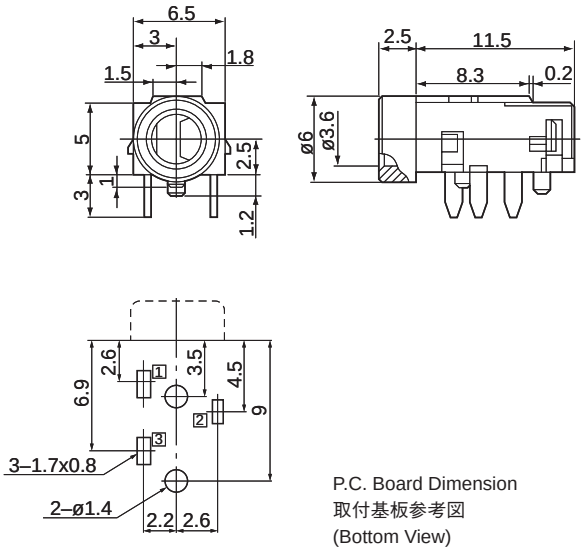


Flow Soldering
フローはんだ

LGY2502-0200F

DIP Type

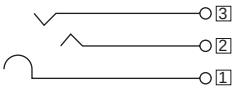
ディップタイプ



[t=1.2/1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

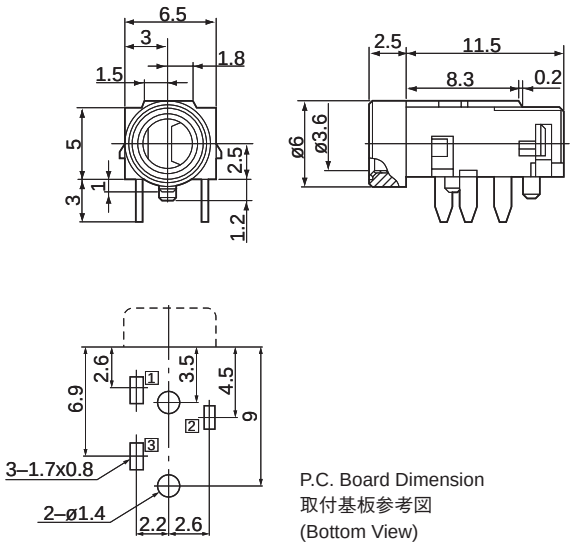


Flow Soldering
フローはんだ
(Please contact about soldering condition)
(はんだ条件について、ご相談ください。)
Manual Soldering
手はんだ

LGY2512-0100F

DIP Type

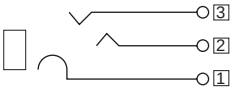
ディップタイプ



[t=1.2/1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

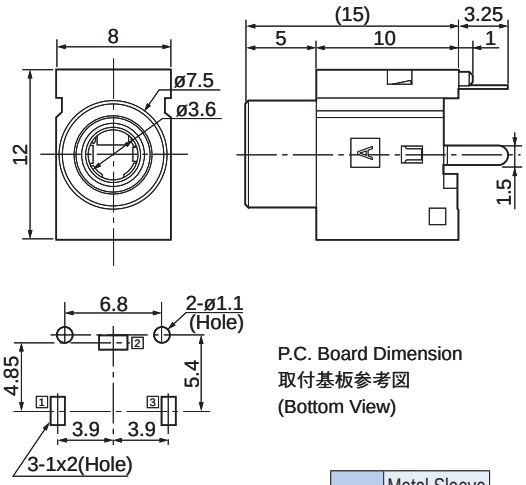
Circuits / 回路



Flow Soldering
フローはんだ
(Please contact about soldering condition)
(はんだ条件について、ご相談ください。)
Manual Soldering
手はんだ

3.5mm Dia. Jacks

LGT10□2-0100F



[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

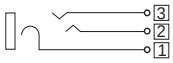
□	Metal Sleeve 口金
0	Without
1	With

※ Pattern compatible with LGM10 □ 9
LGM10 □ 9 とパターンコンパチ

DIP Type

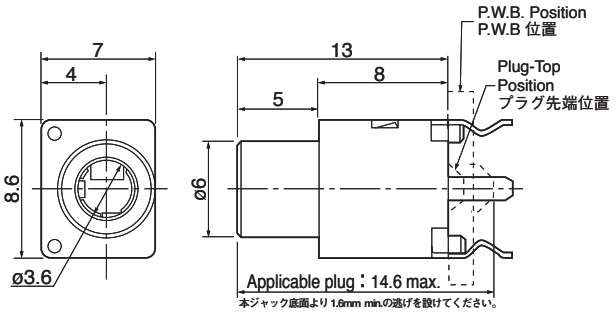
ディップタイプ

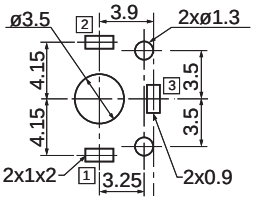
Circuits / 回路



Manual Soldering
手はんだ

LGT8002-0100F





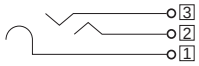
[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

DIP Type

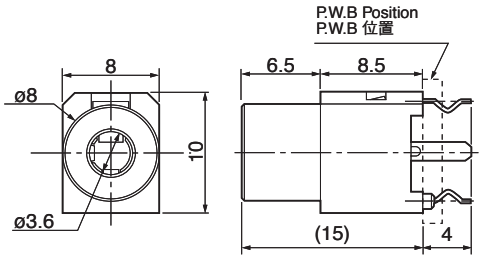
ディップタイプ

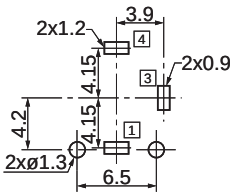
Circuits / 回路



Manual Soldering
手はんだ

LGT8502-0200F





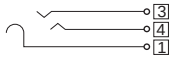
[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

DIP Type

ディップタイプ

Circuits / 回路



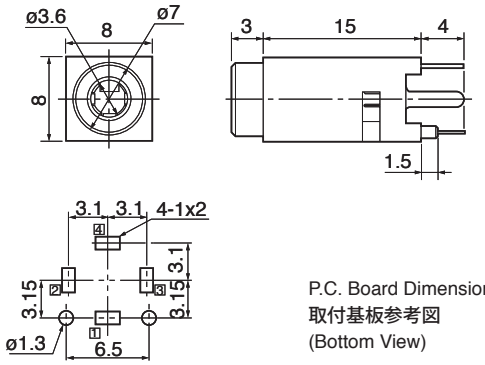
Flow Soldering
フローはんだ
Manual Soldering
手はんだ

3.5mm Dia. Jacks

LGT1509-0200F

DIP Type

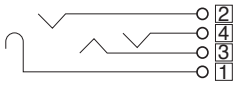
ディップタイプ



[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路



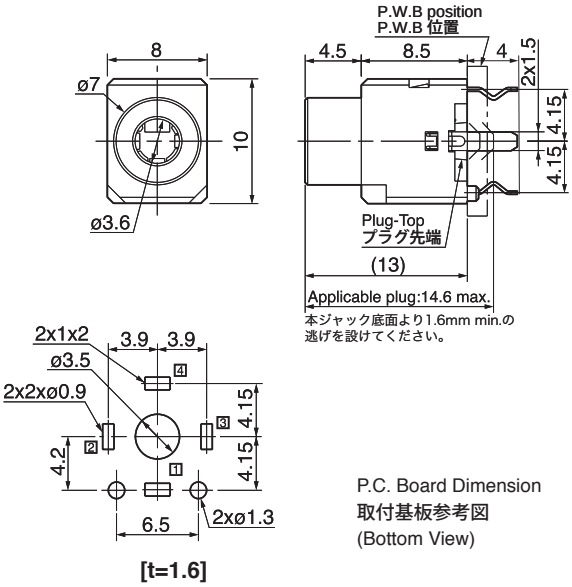
Flow Soldering
フローはんだ

Manual Soldering
手はんだ

LGT8509-0300F

DIP Type

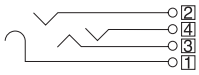
ディップタイプ



[t=1.6]

P.C. Board Dimension
取付基板参考図
(Bottom View)

Circuits / 回路

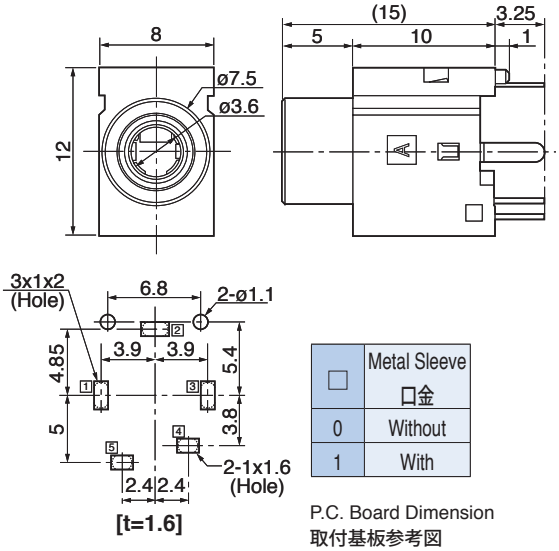


Manual Soldering
手はんだ

LGM10□9-0100F

DIP Type

ディップタイプ



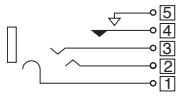
[t=1.6]

□	Metal Sleeve 口金
0	Without
1	With

P.C. Board Dimension
取付基板参考図
(Bottom View)

※Pattern compatible with LGT10□2
LGT10□2とパターンコンパチ

Circuits / 回路



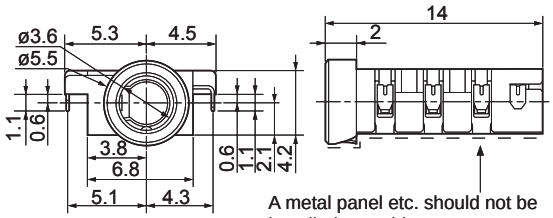
Manual Soldering
手はんだ

3.5mm Dia. Jacks

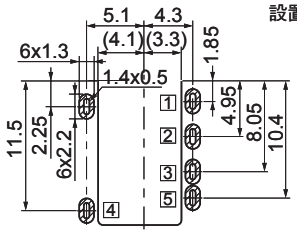
LGY0609-0600F

Mid Mount Type

ミッドマウントタイプ



A metal panel etc. should not be installed near this area.
このエリア付近には、金属パネル等を設置しないでください。

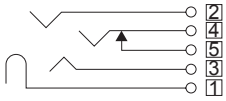


(Land)

[t=0.8]

P.C. Board Dimension
取付基板参考図
(Top View)

Circuits / 回路



Reflow Soldering
リフローはんだ
Manual Soldering
手はんだ